UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO. : 6,809,532 B2 APPLICATION NO. : 10/063869

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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Col. 6, line 21, Claim 1 should read as follows: 1.An inspection method for a semiconductor circuit with a plurality of connected semiconductor devices comprising the steps of applying an electrical load on the circuit, taking a photograph of the circuit with a thermographic camera to detect heat development of each semiconductor device in response to the applied load, and processing the photograph to determine the temperature of the semiconductor devices for determining the quality of circuit and semiconductor devices based on the heat development.

Col. 6, line 39, Claim 4 should read as follows: 4.An inspection apparatus for a workpiece consisting of a semiconductor circuit with a plurality of connected semiconductor comprising an apparatus body on which a workpiece to be inspected is set, a loading circuit for applying load corresponding to the condition of use to the workpiece, a power source for supplying a working current to the workpiece through said loading circuit, a drive waveform generating circuit for applying a drive signal to said workpiece, a thermographic camera for taking photographs of the workpiece set on said apparatus body, an image processor connected to said thermographic camera for determining the temperatures of said semiconductor devices solely from the output of said thermographic camera, and a control for controlling said inspection apparatus to perform an inspection program.

Signed and Sealed this

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Seventh Day of August, 2007

JON W. DUDAS
Director of the United States Patent and Trademark Office